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**Product
Bulletin**

900-03

MICROSORB D-RDF
 LIGHT-WEIGHT, LOW DIELECTRIC
 STRUCTURAL FOAM

GENERAL DESCRIPTION

MICROSORB D-RDF is rigid, low-dielectric sheet-stock foam.

MICROSORB D-RDF has excellent physical and dielectric properties. It can be machined to tight tolerances.

MICROSORB D-RDF is useful for high temperature applications requiring structural strength, as a thermal barrier material, or as an RF window.

MICROSORB D-RDF can be thermoformed. Processing temperatures are approximately 350°F. Because of its versatility, **MICROSORB D-RDF** has applications as a radome core material, and in composite structures.

SIZES

- Standard sheet size 24" x 24"
- Standard Thicknesses available 0.5", 1.0", 2.0"

Other thickness and sizes are available upon request. Contact Microsorb Customer Service.

SPECIFICATIONS

Property	Unit	D-RDF -15	D-RDF -17	D-RDF -11
Density	lbs/ft ³ kg/m ³	3.2 52	4.7 75	7.0 110
Dielectric constant	2-20 GHz	1.09	1.10	1.14
Dissipation factor	5 GHz	0.0004	0.0007	0.0009
Compressive strength	psi (MPa)	130 0.91	215 1.5	430 3.0
Shear strength	psi (MPa)	115 0.8	190 1.3	345 2.4
Flexural Strength	psi (MPa)	230 1.6	360 2.5	650 4.5
Tensile Strength	psi (MPa)	275 1.9	405 2.8	3.5 505
Elastic Modulus	psi (MPa)	10,150 70	13,300 92	23,200 160
Shear Modulus	psi (MPa)	2,775 19	4,200 29	7,250 50
Elongation at Break	%	4.0	4.5	4.5
Heat Distortion Resistance	°F (°C)	356 180	356 180	356 180
Thermal Conductivity	Btu/(hr.ft ² .°F/ft) (cal)/(sec)(cm ²) (°C)/(cm)	0.16	0.28	0.31
Service Temperature, Max	°F (°C)	356 180	356 180	356 180

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